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components is no longer necessary.

REMARKS

The abstract has been amended to eliminate the term "comprises" objected to by the Examiner as being legal phraseology.

The rejection of Claims 1-11 under 35 U.S.C. 102 (b) as anticipated by Hansen et al. is considered to lack merit.

The Hansen et al. patent is not considered to teach, or even suggest, even Claim 1, the most generic claim directed to a an electronic component and Claim 7, the most generic claim directed to a method of manufacturing an electronic component.

Unlike the electronic component defined by Claim 1, the electronic component of the Hansen et al. patent does not have a dielectric which comprises a composite consisting of a dielectric ceramic material and an organic polymer.

As shown in column 2, lines 20-37, the dielectric of the electronic component of the Hansen et al. patent is essentially composed of a dielectric ceramic composition and thus is essentially free of any organic polymer.

Unlike the method defined by Claim 7, in the method of the Hansen et al. patent a dielectric ceramic material is not mixed with a monomer of a polymer to form a mass and the monomer is then partially or completely polymerized.

Instead, in the method of the Hansen et al. patent, a dielectric ceramic material is mixed with a polymer and a solvent to form a suspension, which suspension is then dried and then sintered, column 4, lines 9-32 and Examples 1, 2, 3, 4, 5 and 6.

The rejection of Claim 12 under 35 U.S.C. 103 (b) as anticipated by Hirai et al. is considered to lack merit.

The filter arrangement of the Hirai et al. patent, unlike that defined by Claim 12, does not have an electronic component having a dielectric comprising a composite of a dielectric material and an organic polymer.

Instead, as shown in column 7, line 47-51 the dielectric of the electronic component of the Hirai et al. patent contains no organic polymer, being "made of a ceramic dielectric material".

An early allowance of the claims and case is requested.

The Commissioner is hereby authorized to credit any overpayment or charge any fee (except the issue fee) to Account No. 14-1270.

Respectfully submitted,

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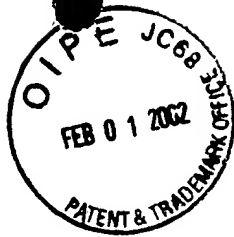
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By Norman N. Spain



APPENDIX

TECHNOLOGY CENTER

The invention describes an electronic component, in particular a multiplayer component, with a dielectric and at least one electrode. The dielectric ~~comprises~~ is a composite made of a dielectric ceramic material and an organic polymer. To manufacture the electronic component, the dielectric ceramic material is mixed with a suitable monomer, the mass is formed, and the monomer is polymerized. Ceramic bodies of stable shape are obtained which can be processed further into capacitors, antennas, or other passive components in that electrodes are provided. Sintering of the electronic components is no longer necessary.